

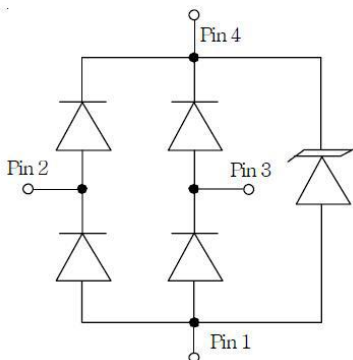
Description

The SR05 is a 2-line ultra-low capacitance TVS di-ode array, utilizing leading monolithic silicon technology to provide fast response time and low ESD clamping voltage, making this device an ideal solution for protecting voltage sensitive high-speed data lines. The SR050 has a very low capacitance with a typical value at 0.3pF, and complies with the IEC 61000-4-2 (ESD) with $\pm 25kV$ air and $\pm 20kV$ contact discharge. It is assembled into a 4-pin SOT-143 lead-free package. The small size, very low capacitance and high ESD surge protection make SEH0503S1 an ideal choice to protect cell phone, digital video interfaces, high speed data ports, and many other portable applications. .

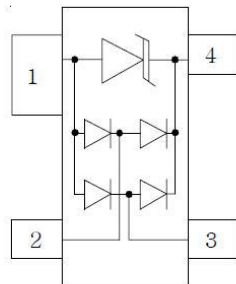
Features

- Ultra low capacitance: 0.3pF typical
- Working voltage: 5V
- Low clamping voltage
- Protects two data lines and one power line
- Complies with following standards:
 - IEC 61000-4-2 (ESD) immunity test
 - Air discharge: $\pm 25kV$
 - Contact discharge: $\pm 20kV$
 - IEC61000-4-4 (EFT) 40A (5/50ns)
 - IEC61000-4-5 (Lightning) 5A (8/20 μs)
- RoHS Compliant

Dimensions & Symbol (Unit: mm Max)



Circuit Diagram



Pin Schematic

Mechanical Characteristics

- Package: SOT-143
- Lead Finish: NiPdAu
- Case Material: “Green” Molding Compound.
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminal Connections: See Diagram Below
- Marking Information: See Below

Applications

- Cellular Handsets and Accessories
- Display Ports
- MDDI Ports
- USB Ports
- Digital Visual Interface (DVI)
- PCI Express and Serial SATA Ports

Marking Information



Ordering information

Part Number	Packaging	Reel Size
SR05	3000/Tape & Reel	7 inch

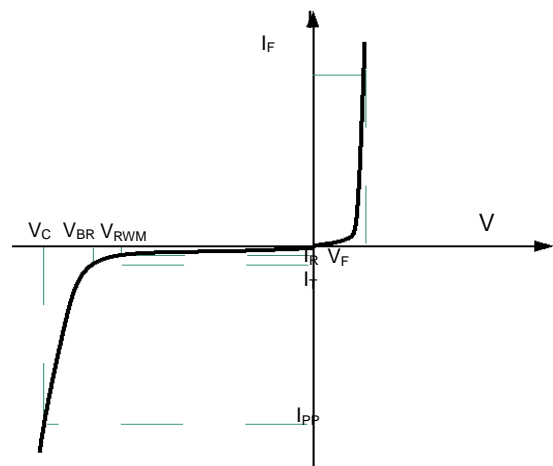
Absolute maximum ratings ($T_A=25^{\circ}\text{C}$, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak Pulse Power (tp=8/20μs waveform)	P_{ppp}	75	W
Peak Pulse Current (8/20μs)	I_{pp}	5	A
ESD per IEC 61000-4-2 (Air)	V_{ESD}	±25	kV
ESD per IEC 61000-4-2 (Contact)		±20	
Operating Temperature Range	T_J	-55 to +125	°C
Storage Temperature Range	T_{stg}	-55 to +150	°C

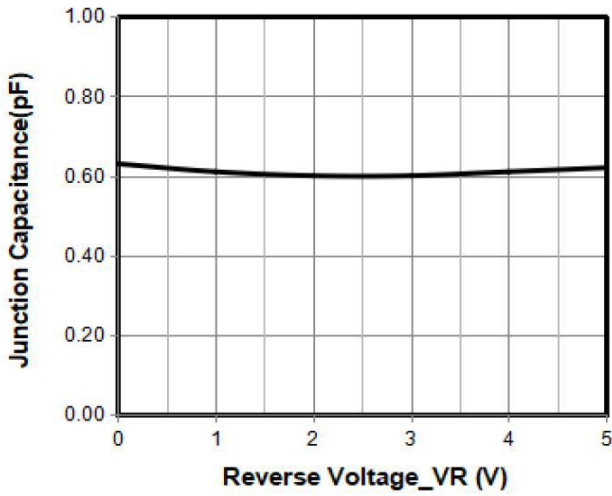
Electrical characteristics ($T_A=25^{\circ}\text{C}$)

Parameter	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Working Voltage	V_{RWM}			5.5	V	
Breakdown Voltage	V_{BR}	6			V	$I_T = 1\text{mA}$
Reverse Leakage Current	I_R			0.5	μA	$V_{RWM} = 5.0\text{V}$
Clamping Voltage	V_C			10	V	$I_{PP} = 1\text{A}$ (8 x 20μs pulse)
Clamping Voltage	V_C			15	V	$I_{PP} = 5\text{A}$ (8 x 20μs pulse)
Junction Capacitance	C_J		0.6	0.9	pF	$V_R = 0\text{V}$, $f = 1\text{MHz}$, any I/O pin to ground
Junction Capacitance	C_J		0.5		pF	$V_R = 0\text{V}$, $f = 1\text{MHz}$, between I/O pins

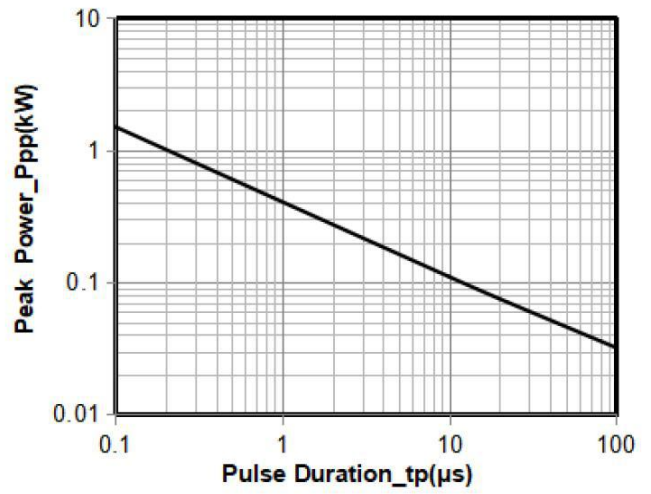
Symbol	Parameter
V_{RWM}	Peak Reverse Working Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
P_{PP}	Peak Pulse Power
C_J	Junction Capacitance
I_F	Forward Current
V_F	Forward Voltage @ I_F



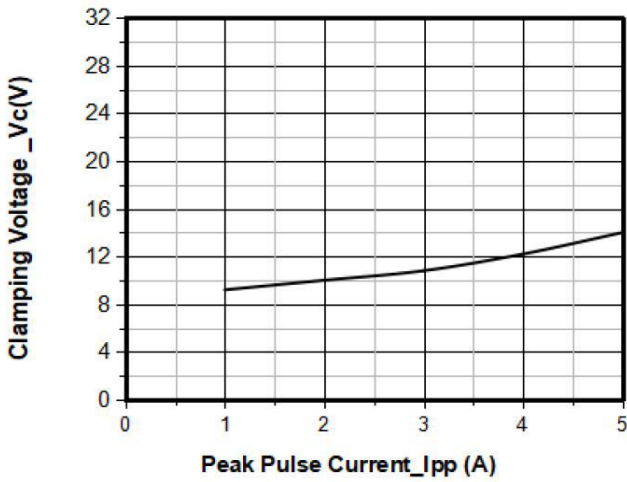
Typical Performance Characteristics ($T_A=25^{\circ}\text{C}$ unless otherwise Specified)



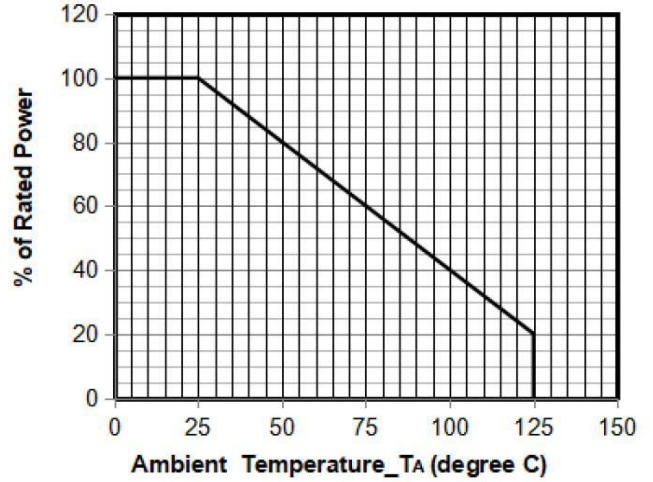
Junction Capacitance vs. Reverse Voltage



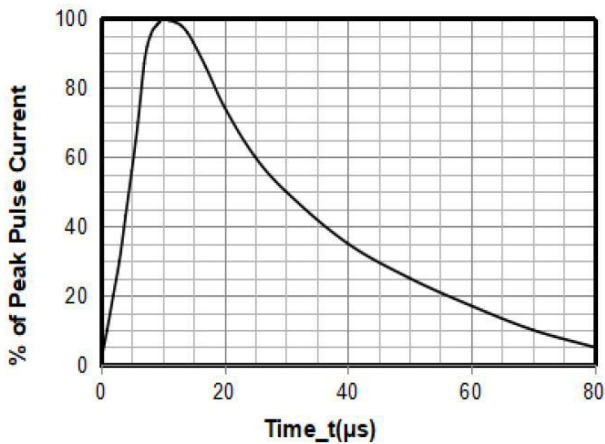
Peak Pulse Power vs. Pulse Time



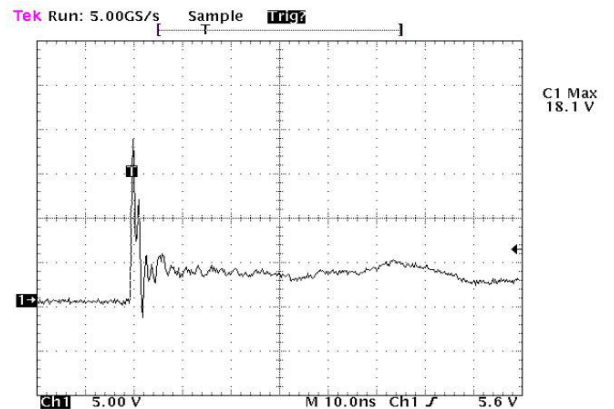
Clamping Voltage vs. Peak Pulse Current



Power Derating Curve



8 X 20μs Pulse Waveform



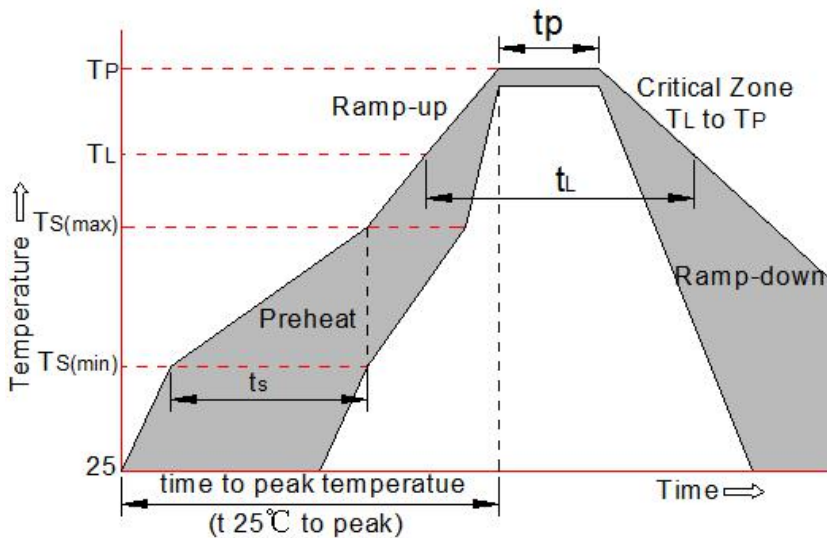
Note: Data is taken with a 10x attenuator

ESD Clamping Voltage

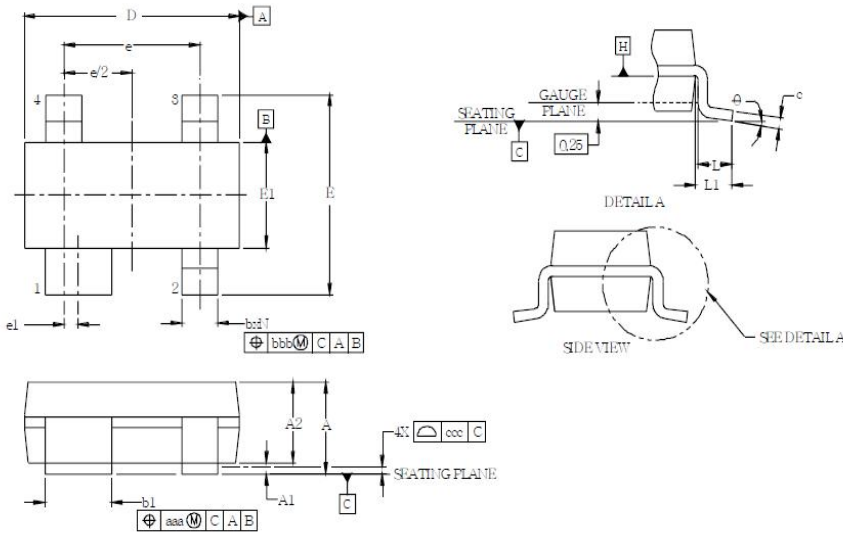
8 kV Contact per IEC61000-4-2

Soldering Parameters

Reflow Condition		Pb-Free assembly (see as bellow)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (t_s)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L) (Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C

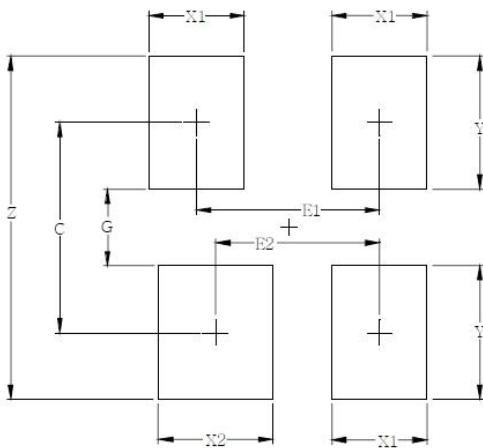


Package Mechanical Data



SYM	DIMENSIONS		
	MILLIMETERS		
	MIN	NOM	MAX
A	0.80	-	1.22
A1	0.013	-	0.15
A2	0.75	0.90	1.07
b	0.30	-	0.51
b1	0.76	-	0.94
c	0.08	-	0.20
D	2.80	2.90	3.04
E	2.10	2.37	2.64
E1	1.20	1.30	1.40
e	1.92BSC		
e1	0.20BSC		
L	0.40	0.50	0.60
L1	(0.54)		
N	4		
θ	0°	-	8°

Suggested Land Pattern



SYM	DIMENSIONS	
	MILLIMETERS	INCHES
C	2.20	0.087
E1	1.92	0.076
E2	1.72	0.068
G	0.80	0.031
X1	1.00	0.039
X2	1.20	0.047
Y	1.40	0.055
Z	3.60	0.141